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ABSTRACT OF THE DISCLOSURE:

PHOTOSENSITIVE RESIN COMPOSITION AND PRINTED WIRING BOARD

- 5 Disclosed is a photosensitive resin composition for use as a solder resist, which is free from anti-tackiness and excellent in flexibility, adhesiveness and heat resistance without other film properties being sacrificed, and can be easily designed so as to obtain properties in conformity with the end use thereof. This photosensitive resin composition comprising (A) an active energy ray-curable resin having at least two
- 10 ethylenic unsaturated linkages per molecule, (B) a photopolymerization initiator, (C) a reactive diluent, and (D) a thermosetting compound; wherein said (A) comprises a resin which is obtained by a process wherein an epoxy compound is successively reacted with a unsaturated monocarboxylic acid and with a polybasic acid to form a compound, which is then allowed to react with a novolac epoxy resin to obtain the
- 15 resin. There is also disclosed a printed wiring board formed using the aforementioned photosensitive resin composition.



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